Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

**S SOURCE**

**D DRAIN**

**37 mils**

**25 mils**

**S**

**D**

**BACKSIDE IS GATE**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Gate**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .025” X .037” DATE: 4/5/16**

**MFG: NATIONAL THICKNESS .008” P/N: 2N5434**

**DG 10.1.2**

#### Rev B, 7/19/02